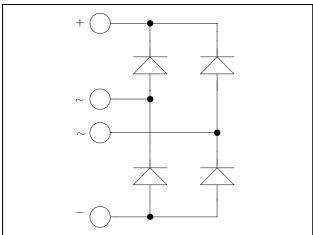


ISOTOP® Fast Diode Full Bridge Power Module

 $V_{RRM} = 600V$ $I_F = 30A @ Tc = 80°C$



+000

Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration
- ISOTOP® Package (SOT-227)

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit	
V_R	Maximum DC reverse Voltage			600	V	
V_{RRM}	Maximum Peak Repetitive Revers	e Voltage			000	V
$I_{F(AV)}$	Maximum Average Forward	D 4	500/	$T_C = 25^{\circ}C$	60	
	Current	Duty cycl	e = 50%	$T_C = 80$ °C	30	A
I_{FSM}	Non-Repetitive Forward Surge Cu	rrent 8.3ms		$T_J = 45^{\circ}C$	320	

TAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$V_{\rm F}$	Diode Forward Voltage	$I_F = 30A$	= 30A		1.8	2.2	V
		$I_F = 60A$			2.2		
		$I_F = 30A$	$T_{j} = 125^{\circ}C$		1.5		
I_{RM}	Maximum Reverse Leakage Current	$V_R = 600V$ $T_i = 25^{\circ}C$ $T_j = 125^{\circ}C$	$T_i = 25^{\circ}C$			250	4
			$T_j = 125$ °C			500	μΑ
C_{T}	Junction Capacitance	$V_R = 200V$			36		pF

Dynamic Characteristics

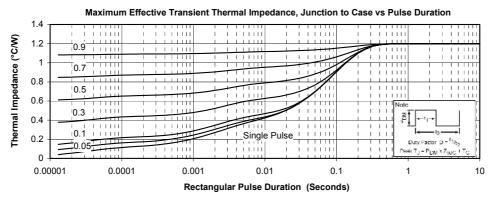
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t _{rr}	Reverse Recovery Time		$T_j = 25^{\circ}C$		25		ns
			$T_{j} = 125^{\circ}C$		160		
Q _{rr}	Reverse Recovery Charge	$I_F = 30A$ $V_R = 400V$	$T_j = 25^{\circ}C$		35		nC
Qrr		$di/dt = 200A/\mu s$	$T_{i} = 125^{\circ}C$		480		
т	Reverse Recovery Current		$T_j = 25^{\circ}C$		3		A
I_{RRM}			$T_j = 125$ °C		6		
t_{rr}	Reverse Recovery Time	$I_F = 30A$ $V_R = 400V$ $di/dt = 1000A/\mu s$			85		ns
Q _{rr}	Reverse Recovery Charge		$T_j = 125$ °C		920		nC
I_{RRM}	Reverse Recovery Current				20		A

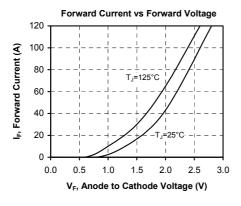
Thermal and package characteristics

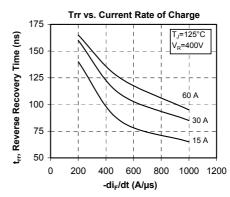
Symbol	Characteristic	Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal resistance			1.2	°C/W
R_{thJA}	Junction to Ambient			20	C/ W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	2500			V
T_J, T_{STG}	Storage Temperature Range	-55		175	°C
$T_{ m L}$	Max Lead Temp for Soldering:0.063" from case for 10 sec			300	C
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

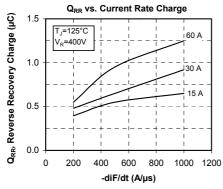


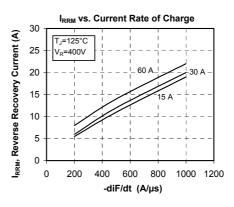
Typical Performance Curve

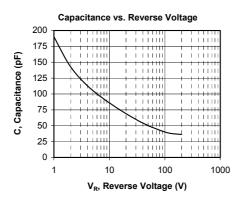






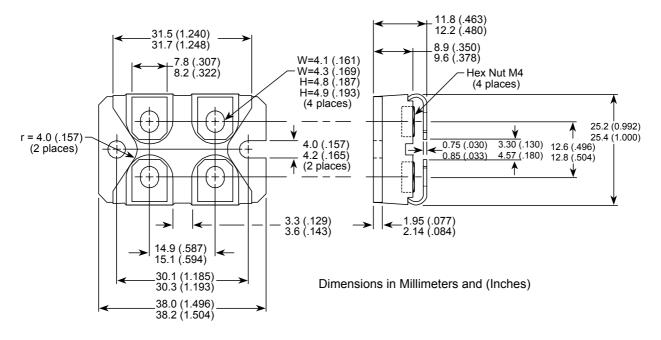








SOT-227 (ISOTOP®) Package Outline



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